

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	129245	(chip\$1 semiconductor die).ti.	US-PGPUB; USPAT	OR	ON	2006/07/13 21:12
L2	590794	(chip\$1 semiconductor adj element semiconductor adj device)	US-PGPUB; USPAT	OR	ON	2006/07/13 21:03
L3	590812	(chip\$1 semiconductor adj elements\$2 semiconductor adj device\$2)	US-PGPUB; USPAT	OR	ON	2006/07/13 21:12
L4	18128	(solder\$2)near5(connect\$4 coupl\$4)near5(substrate board base)	US-PGPUB; USPAT	OR	ON	2006/07/13 21:13
L5	12566	(solder\$2)near5 (underlayer barrier\$2 adhesive)	US-PGPUB; USPAT	OR	ON	2006/07/13 21:13
L6	681	1 and 3 and 4 and 5	US-PGPUB; USPAT	OR	ON	2006/07/13 21:05
L7	9083	solder\$2 with((precious adj2 metal)or gold or Au or silver or Ag or pt or pd)near10 (tin or Sn or Pb or lead)	US-PGPUB; USPAT	OR	ON	2006/07/13 21:13
L8	15220	(gold\$1sn au\$1sn au near2 sn gold\$1tin gold near3 tin)	US-PGPUB; USPAT	OR	ON	2006/07/13 21:14
L9	139	6 and 7	US-PGPUB; USPAT	OR	ON	2006/07/13 21:25
L10	90	6 and 8	US-PGPUB; USPAT	OR	ON	2006/07/13 21:07
L11	62	9 not 10	US-PGPUB; USPAT	OR	ON	2006/07/13 21:07
L12	13	10 not 9	US-PGPUB; USPAT	OR	ON	2006/07/13 21:08
L13	951056	(chip\$1 semiconductor die).ti.	EPO; JPO; DERWENT	OR	ON	2006/07/13 21:12
L14	713704	(chip\$1 semiconductor adj element\$2 semiconductor adj device\$2)	EPO; JPO; DERWENT	OR	ON	2006/07/13 21:12
L15	6717	(solder\$2)near5(connect\$4 coupl\$4)near5(substrate board base)	EPO; JPO; DERWENT	OR	ON	2006/07/13 21:13
L16	3891	(solder\$2)near5 (underlayer barrier\$2 adhesive)	EPO; JPO; DERWENT	OR	ON	2006/07/13 21:13
L17	30706	((precious adj2 metal)or gold or Au or silver or Ag or pt or pd)near10 (tin or Sn or Pb or lead)	EPO; JPO; DERWENT	OR	ON	2006/07/13 21:13
L18	3518	(gold\$1sn au\$1sn au near2 sn gold\$1tin gold near3 tin)	EPO; JPO; DERWENT	OR	ON	2006/07/13 21:14

## EAST Search History

L19	31	13 and 14 and 15 and 16	EPO; JPO; DERWENT	OR	ON	2006/07/13 21:17
L20	114	17 and 16	EPO; JPO; DERWENT	OR	ON	2006/07/13 21:24
L21	0	17 and 19	EPO; JPO; DERWENT	OR	ON	2006/07/13 21:23
L22	52	18 and 16	EPO; JPO; DERWENT	OR	ON	2006/07/13 21:24
L23	25	18 and 16 and 13	EPO; JPO; DERWENT	OR	ON	2006/07/13 21:24
L24	1293	257/26 257/772 257/779.ccls.	US-PGPUB; USPAT	OR	ON	2006/07/13 21:25
L25	0	19 and 24	US-PGPUB; USPAT	OR	ON	2006/07/13 21:25
L26	17	9 and 24	US-PGPUB; USPAT	OR	ON	2006/07/13 21:25